0.0±0.2

Unit: mm

.2±0.2

2.7±0.2

4.2±0.2

¢3.1±0.1

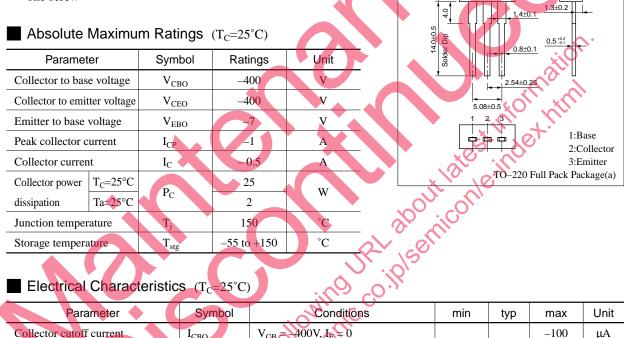
2SA1614

Silicon PNP triple diffusion planar type

For high-speed switching

Features

- High-speed switching •
- High collector to base voltage V_{CBO} ٠
- Wide area of safe operation (ASO) •
- Satisfactory linearity of foward current transfer ratio h_{FE} •
- Full-pack package which can be installed to the heat sink with • one screw

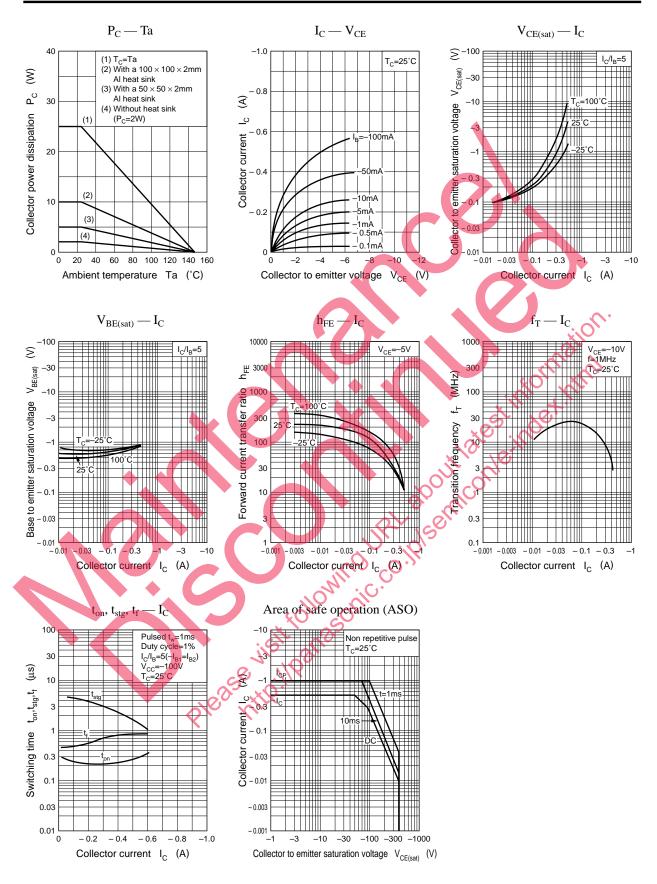


Electrical Characteristics (T_c=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I _{CBO}	$V_{CB} = -400V, I_{E} = 0$			-100	μΑ
Emitter cutoff current	I _{EBO}	$V_{EB} = -7V$, $I_C = 0$			-100	μΑ
Collector to emitter voltage	V _{CEO}	$I_{\rm C} = -t0{\rm mA}, I_{\rm B} = 0$	-400			V
	h _{FE1} *	$V_{\rm OE} = -5V, I_{\rm C} = -50 {\rm mA}$	80		280	
Forward current transfer ratio	h _{FE2}	$V_{\rm CE} = -5V, I_{\rm C} = -0.3A$	10			
Collector to emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = -0.2 {\rm A}, I_{\rm B} = -40 {\rm mA}$			-1.5	V
Base to emitter saturation voltage	V _{BE(sat)}	$I_{\rm C} = -0.2$ A, $I_{\rm B} = -40$ mA			-1.5	V
Transition frequency	f_T	$V_{CE} = -10V, I_C = -0.1A, f = 1MHz$		20		MHz
Turn-on time	ton	$I_{\rm C} = -0.3 {\rm A},$		0.25		μs
Storage time	t _{stg}	$I_{B1} = -60 \text{mA}, I_{B2} = 60 \text{mA},$		2.0		μs
Fall time	t _f	$V_{CC} = -200V$		0.5		μs

^{*}h_{FE1} Rank classification

Rank	Q	Р		
h _{FE1}	80 to 160	130 to 280		





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